



### 1. Features:

The features of LCD are as follows:

- Display mode : STN /BLUE, POSITIVE, TRANSMISSIVE
- Colour : Display dot : WHITE
   Background: BLUE
- Display Format : 240x64 Dots
- \* IC : RA6963
- Interface Input Data : 8 Bits
- Driving Method : 1/64 Duty, 1/9 Bias
- Viewing Direction: 6 O'clock
- Backlight : LED (WHITE)

### 2. Mechanical Specifications:

Item	Specification	Unit
Module Size	180.00(W) X65.00(H) X13.30(T)	mm
Viewing Area	132.00(W) X 39.00(H)	mm
Effective Display Area	127.16(W) X33.88(H)	mm
Number of Dots	240x64	-

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Dot Size	0.49(W) X 0.49(H)	mm
Dot Pitch	0.54(W) X 0.54(H)	mm





### **3. Electrical Specifications:**

#### **1.** Absolute Maximum Ratings (Vss = 0V)

ltem	Symbol	St	Unit		
Rem	Oymbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd	-0.3	-	7.0	V
Supply Voltage For LCD Drive	V0, Vouт	12	12.2	12.4	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Ts⊤	-30	-	+80	°C
Static Electricity	Bes	sure that you	are ground w	hen handing	LCM

#### 2. Electrical Characteristics:

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Supply Voltage For Logic		Vdd – Vss	<b>Ta=25</b> ℃	4.8	5.0	5.2	V
Supply Voltage For LCD		Vdd – Vo	- V₀ <b>Ta=25</b> ℃		12.2	12.4	V
	"H" Lev <mark>el</mark>	V IH	<b>Ta=25</b> ℃	0.8Vdd	-	Vdd	V
Input Voltage	"L" Level	V IL	Ta=23 C	Vss	-	0.2Vdd	V
Output Voltage	"H" Level	V <sub>OH</sub>	I <sub>OUT</sub> = -0.5mA	0.8VDD	-	Vdd	V
Oulput voltage	"L" Level	V <sub>ol</sub>	I <sub>OUT</sub> = 0.5mA	Vss	-	0.2Vdd	V
Current Consumption		I <sub>DD</sub>	$V_{IN} = V_{DD}$	-	-	1.0	mA

NOTE: 1) Duty ratio=1/65, Bias=1/9 2) Measured in Dots ON-state



#### **3. BACKLIGHT:**

#### **3.1** Absolute Maximum Ratings:

Item	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Current	IF	<b>Ta=25</b> ℃	-	-	20	mA
Reverse Voltage	VR	1a=25 C	-	-	5	V
Power Dissipation	PD	<b>Ta= 25</b> ℃	-	-	100	mW

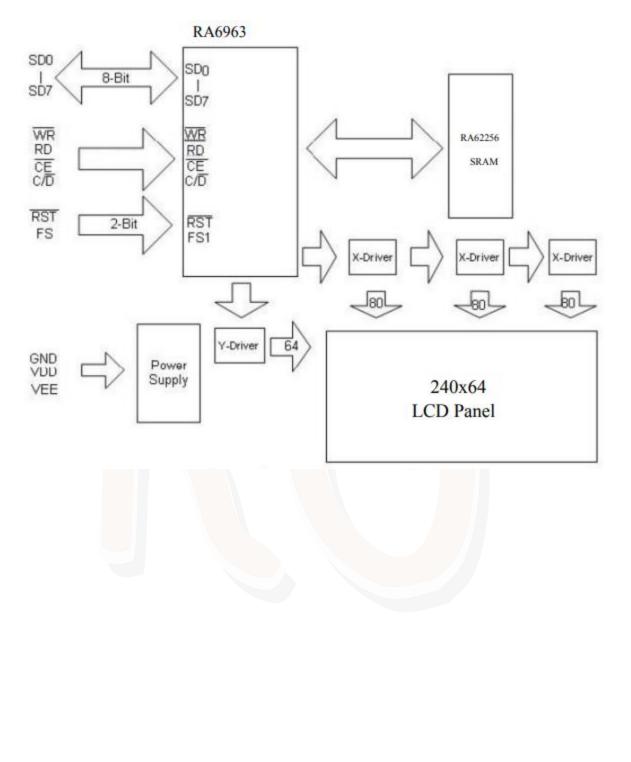
### **3.2** Opto-electronic Characteristics:

ltem	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	Ta= 25℃	4.8	5.0	5.2	V
Luminous	-	IF= 130mA	100	150	-	cd/m²

\* The brightness is measured without LCD panel



# 4. Schematic Design:





# **5. Interface Pin Function:**

Pin No.	Symbol	Level	Description
1	FG	_	Mounting holes grounding
2	Vss	0V	Ground
3	Vdd	5.0V	Supply voltage for logic (option +3.3V)
4	Vo	_	Operating voltage for LCD
5	WR	H/L	White signal, active "L".
6	RD	H/L	Read signal, active "L".
7	CE	H/L	Chip enable signal, active "L".
8	C\D	H/L	H: Instruction code; L: Data.
9	NC	_	No connection
10	/RST	L	Reset signal
11	DB0	H/L	Data bus line 0
12	DB1	H/L	Data bus line 1
13	DB2	H/L	Data bus line 2
14	DB3	H/L	Data bus line 3
15	DB4	H/L	Data bus line 4
16	DB5	H/L	Data bus line 5
17	DB6	H/L	Data bus line 6
18	DB7	H/L	Data bus line 7
19	FS	H/L	Selection of font H:6 X 8, L=8 X 8
20	VOUT	_	Negative Voltage output -18.5 V
21	LEDA	_	Power supply for B/L (+)
22	LEDK	_	Power supply for B/L (GND)



# 6. Command List:

COMMAND	CODE	D1	D2	FUNCTION		
	00100001	X address	Y address	Set Cursor Pointer		
REGISTERS SETTING	00100010	Data	00H	Set Offset Register		
	00100100	Low address	High address	Set Address Pointer		
	01000000	Low address	High address	Set Text Home Address		
SET CONTROL WORD	01000001	Columns	00H	Set Text Area		
SET CONTROL WORD	01000010	Low address	High address	Set Graphic Home Address		
	01000011	Columns	00H	Set Graphic Area		
	1000X000	-	-	OR mode		
	1000X001	-	-	EXOR mode		
MODE SET	1000X011	-	-	AND mode		
	1000X100	-	-	Text Attribute mode		
	10000XXX	-	-	Internal CG ROM mode		
	10001XXX	_	_	External CG RAM mode		
	10010000	-	-	Display off		
	1001XX10	-	-	Cursor on, blink off		
DISPLAY MODE	1001XX11	_	_	Cursor on, blink on		
DISPLAY MODE	100101XX	-	- 1	Text on, graphic off		
	100110XX	_	_	Text off, graphic on		
	100111XX	_	-	Text on, graphic on		
	10100000	_	-	1-line cursor		
	10100001	_	-	2-line cursor		
	10100010	_	_	3-line cursor		
CURSOR PATTERN	10100011	_	_	4-line cursor		
SELECT	10100100	-	-	5-line cursor		
	10100101	-	-	6-line cursor		
	10100110	_	_	7-line cursor		
	10100111	_	_	8-line cursor		
	10110000	_	_	Set Data Auto Write		
DATA AUTO READ/ WRITE	10110001	_	_	Set Data Auto Read		
WKITE	10110010	-	-	Auto Reset		
	11000000	Data	_	Data Write and Increment ADP		
	11000001	_	_	Data Read and Increment ADP		
	11000010	Data	_	Data Write and Decrement ADP		
DATA READ/WRITE	11000011	-	_	Data Read and Decrement ADP		
	11000100	Data	_	Data Write and Nonvariable ADP		
	11000101	_	_	Data Read and Nonvariable ADP		
SCREEN PEEK	11100000	_	_	Screen Peek		
SCREEN COPY	11101000			Screen Copy		



# **Command List (Continued)**

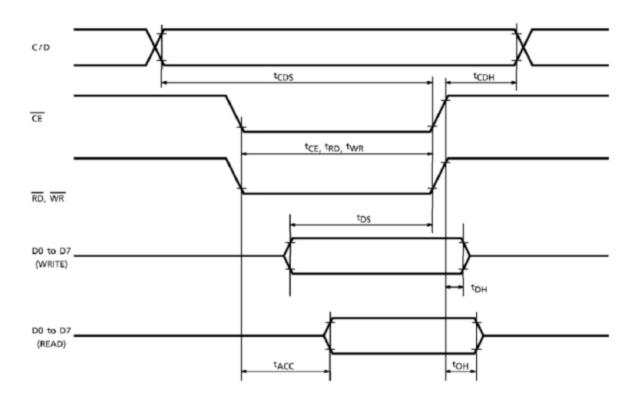
COMMAND	CODE	D1	D2	FUNCTION
	11110XXX	-	-	Bit Reset
	11111XXX	_	-	Bit Set
	1111X000	-	-	Bit O (LSB)
	1111X001	-	-	Bit 1
BIT SET/RESET	1111X010	-	-	Bit 2
BIT SET/RESET	1111X011	-	-	Bit 3
	1111X100	-	-	Bit 4
	1111X101	-	-	Bit 5
	1111X110	-	-	Bit 6
	1111X111	_	-	Bit 7 (MSB)

### FONT BALE

LSB MSB	0	1	2	3	4	5	6	7	8	9	А	В	с	D	E	F
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# 7. Timing Characteristics (Continued):



ITEM	SYMBOL	TEST CONDITIONS	MIN	MAX	UNIT
C/D Set-up Time	tcds	—	100	—	ns
C/D Hold Time	<sup>t</sup> CDH	—	10	—	ns
CE, RD, WR Pulse Width	t <sub>CE</sub> , t <sub>RD</sub> , t <sub>WR</sub>	—	80	—	ns
Data Set-up Time	t <sub>DS</sub>	—	80	—	ns
Data Hold Time	tDH	—	40	—	ns
Access Time	tACC	—	—	150	ns
Output Hold Time	tон	—	10	50	ns



### 8. Quality Specification (Continued):

### 8-3. Sampling Plan and Acceptance

### 1. Sampling Plan

MIL - STD - 105E ( **II** ) ordinary single inspection is used.

#### 2. Acceptance

Major defect:	AQL = 0.25%
Minor defect:	AQL = 0.65%

#### 8-4. Criteria

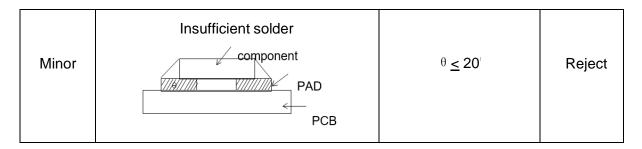
#### a) COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Maj <mark>or</mark>	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

### b) SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	$\begin{array}{c} x \\ x \\ y \\ y \\ z \\ z$	X < 3/4Z Y > 1/3D	Reject Reject
Minor	soldering pad Component tilt	Y > 1/3D	Reject





### c) Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards				
Major	Crack / breakage	Anywher	Reject			
		w		Acceptable of Scratch		
		w<0.03mm	Any	Ignore		
		0.03mm <u>&lt;</u> w<0.05mm	L <u>&lt;</u> 5.0mm	2		
Minor	Frame Scratch	0.05mm <w<0.1mm< td=""><td>L&lt;3.0mm</td><td>1</td></w<0.1mm<>	L<3.0mm	1		
		w> <mark>0.1mm</mark>	Any	0		
		Note: 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.				
				Acceptable of Dents / Pricks		
		⊕ <u>&lt;</u> 1.0mr	n	2		
		1.0<⊕ <u>&lt;</u> 1.5	1			
Minor	Frame Dent, Prick	1.5mm>0	Þ	0		
	$\Phi = \frac{L + W}{2}$	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored				
Minor	Frame Deformation	Exceed the dimension of drawing				
Minor	Metal Frame Oxidation	Any rust				



Defect	Inspection Item		Inspection S	tandards
Minor	Tilted soldering		Within the angle <u>+</u> 3°	Acceptable
Minor	Uneven solder joint /bump			Reject
	Hole	$\Phi = L + W$	Expose the conductive line	Reject
Minor		$\Phi$ > 1.0mm	Reject	
Minor	Position shift		Y > 1/3D	Reject
Minor Y			X > 1/2Z	Reject

#### d) Flexible Film Connector (FFC)

#### e) Screw

Defect	Inspection Item	Inspection Standards	
Maj <mark>or</mark>	Screw missing/loosen	R	
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

### f) Heat seal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L+W}{2}$	<b>Φ &gt; 0.2mm</b>	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
WINO		X > 1/2Z	Reject
Major	Conductive line break		Reject



### g) LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards		
		Acceptable number of units		
		⊕ <u>&lt;</u> 0.10mm		
		0.10<⊕ <u>&lt;</u> 0.15mm		
Minor	LED dirty, prick	0.15<⊕ <u>&lt;</u> 0.2mm	1	
		<b>Φ&gt;0.2mm</b>	0	
	The distance between any two spots should Any spot/dot/void outside of viewing area is			
Minor	Protective film tilt	Not fully cover LCD	Reject	
Major	COG coating	Not fully cover ITO circuit	Reject	

### h) Electric Inspection

Defect	Inspection Item	n Inspection Standards	
Maj <mark>or</mark>	Short		Reject
Major	Open		Reject



Defect		Inspect Item	Inspection Standards					ards		
		* Glass Scratch	W		W<0.0	03	0.0	)3 <w<0.0< td=""><td>5</td><td>W&gt;0.05</td></w<0.0<>	5	W>0.05
			L		L<5		L	.<3		Any
Minor	Linear Defect	* Polarizer Scratch	ACC. NO.		1 1			Reject		
		<ul> <li>Fiber and Linear material</li> </ul>	Note	L is th	ne lengt	th and W	/ is the	width of tl	he defe	ect
		* Foreign material	Φ	Φ	<u>&lt;</u> 0.1	<b>0.1&lt;</b> ⊕	<u>&lt;</u> 0.15	<b>0.15</b> <⊅	<u>&lt;</u> 0.2	Ф <b>&gt;0.2</b>
	Black Spot and	between glass and polarizer or glass	ACC. NO.	3EA	/1PC	2		1		0
Minor	Polarizer Pricked	<ul> <li>and glass</li> <li>Polarizer hole or protuberance by external force</li> </ul>	Note			erage dia > 10mm		of the def	ect.Dis	stance between
		* Unobvious	Φ	Φ	<u>&lt;</u> 0.1	<b>0.1&lt;</b> Φ	<u>&lt;</u> 0.15	<b>0.15</b> <₽	<u>&lt;</u> 0.2	Ф <b>&gt;0.2</b>
		transparent foreign material between	ACC. NO.	3EA	/ 1PC	2		1		0
Minor	White Spot and Bubble in polarizer	ble in glass and glass or glass and polarizer			age diameter of the defect.Distance between 10mm.			stance between		
			Φ	Φ	<u>&lt;</u> 0.10	0.10<⊕ <u>&lt;</u> 0.20			<b>Φ&gt;0.2</b>	
				ЗЕА	A/1PC		2			0
Minor	Segment Defect			W is ı	more th	an 1/2 s	egmer	nt width		Reject
	Delet		Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
			Φ	Φ	<u>&lt;</u> 0.10		0.10	< <u>0.20</u>		Ф <b>&gt;0.2</b>
• 41	Protuberant		w		Glue	V	V <u>&lt;</u> 1/2 \$	Seg , W <u>&lt;</u> 0	).2	Ignore
Minor	Segment	$\Phi = (L+W)/2$	ACC. NO.	3E	A/1PC			2		0
				1			1. Seg	ment		1
			В		B <u>&lt;</u> 0.4	1mm	0.4 <b< td=""><td><u>&lt;</u>1.0mm</td><td></td><td>B&gt;1.0mm</td></b<>	<u>&lt;</u> 1.0mm		B>1.0mm
Minor			B-A		B-A<	1/2B		A<0.2		B-A<0.25
	Assembly Mis-		Judg	le	Accep	table		eptable		Acceptable
	alignment	0.35mm				2	. Dot M	/latrix		
			Deformation>0.35mm				Reject			

### i) Inspection Specification of LCD



Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the aboveitems: "Black spot" and "White Spot"
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### 9. Reliability:

NO.	ltem	Condition	Criterion
1	High Temperature Operating	<b>70</b> ℃, 96Hrs	
2	Low Temperature Operating	<b>-20</b> ℃, 96Hrs	
3	High Humidity	40℃, 90%RH, 96Hrs	(R)
4	High Temperature Storage	80℃, 96Hrs	No defect in cosmeticand
5	Low Temperature Storage	-30℃, 96Hrs	operational function allowable.
6	Vibration	Random wave 10 ~ 100Hz Acceleration: 2g 2 Hrs per direction(X,Y,Z)	Total current Consumption shouldbe below double of initial value.
7	Thermal Shock	-10℃ to 25℃ to 60℃ (60Min) (5Min) (60Min) 16Cycles	
8	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	There will be discharged ten times at every discharging voltage cycle. The voltage gap is 1kV.

*Note:* 1) Above conditions are suitable for xinnuoya standard products.

2) For restrict products, the test conditions listed as above must be revised.



### **10. Handling Precaution:**

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizerswhich easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling

the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommendedbelow) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage thepolarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before poweris turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shockand falls from a height.

- To prevent modules from degradation. Do not operate or store them exposeddirectly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.



### Handling Precaution (Continued):

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show darkcolor in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.

- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 60 °C, 90% RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance, for years) for thepurpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is.

Keeping temperature in the specified storage temperature range.

- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
- It is recommendable to crash damaged or unnecessary LCD into pieces and washoff liquid crystal by using solvents such as acetone and ethanol.

Which should be burned up later.

When any liquid crystal leaked out of a damaged glass cell comes in contact withyour hands, please wash it off well with soap and water.



### **11. Outline Dimensions:**

